



Product Change Notification

108559 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 108559 - 01
Change Title: Intel(R) Carrier Grade Server TIGH2U, PCN 108559-01, Product Material, New retention mechanism for optical drive will replace the original mechanism, Reason for Revision: Update TA revision numbers
Date of Publication: January 13, 2009

Key Characteristics of the Change:

Product Material

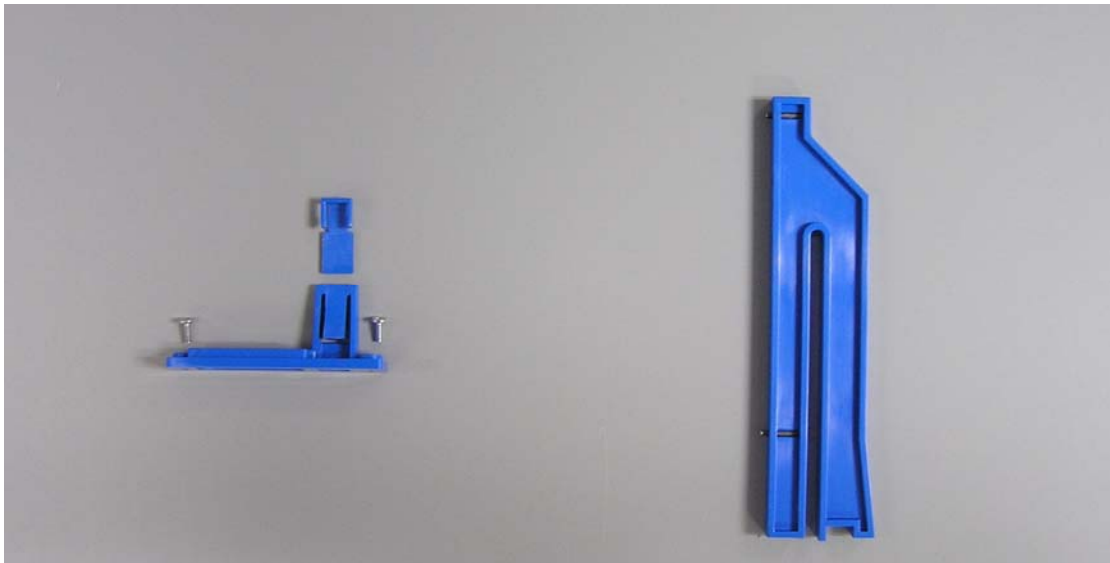
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Oct 13, 2008
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Description of Change to the Customer:

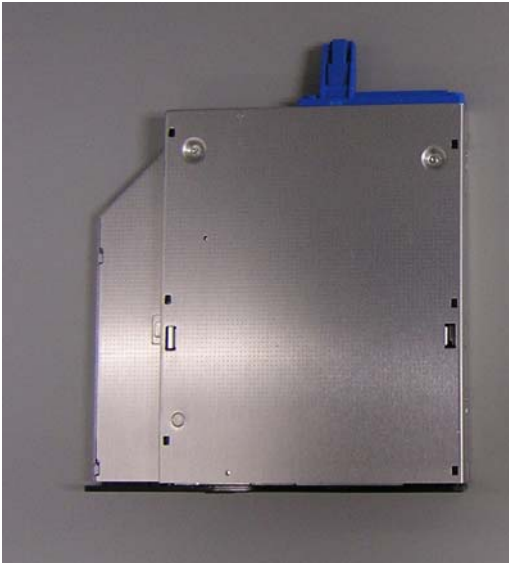
Reason for Revision: Update TA revision numbers

Intel has designed a new optical drive retention mechanism to simplify the installation and removal process of the optical drive. The revised retention mechanism allows removal and replacement of the optical drive without opening the top cover. The original mechanism will be discontinued and replaced by the revised mechanism.

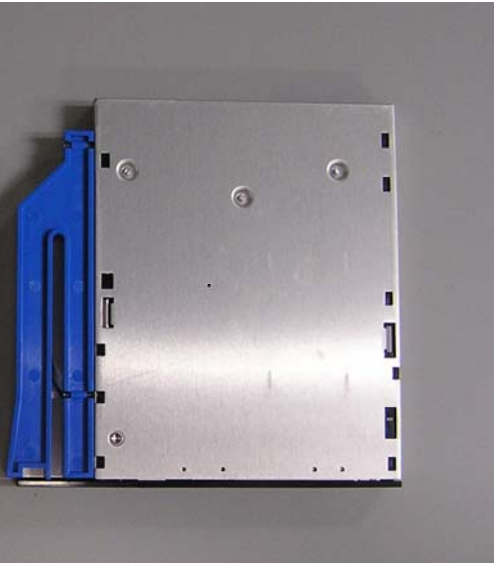


Original optical drive retention mechanism shown on left.

Revised optical drive retention mechanism shown on right.



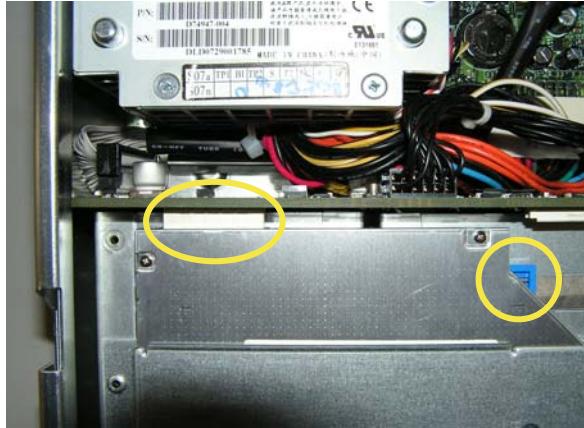
Original **optical drive** retention mechanism attached to drive (underside of CDROM shown)



Revised **optical drive** retention mechanism attached to drive (underside of CDROM shown)



Optical drive installed via original retention mechanism shown on left.



Optical drive installed via revised retention mechanism shown on right.



Optical drive can be removed by moving the lever to the left (see yellow arrow). The lever can be moved with a finger or general tool (like a screwdriver).



Customer Impact of Change and Recommended Action:

Intel anticipates no customer impact based on this change.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Post Change TA
TLHA0201W	890868	E17592-014	E17592-015
TLHD0201W	890910	E17593-014	E17593-015
NSCDVDENGTABW	889845	D89063-004	D89063-005

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
September 11, 2008	00	Originally Published PCN
January 13, 2009	01	Update TA revision numbers